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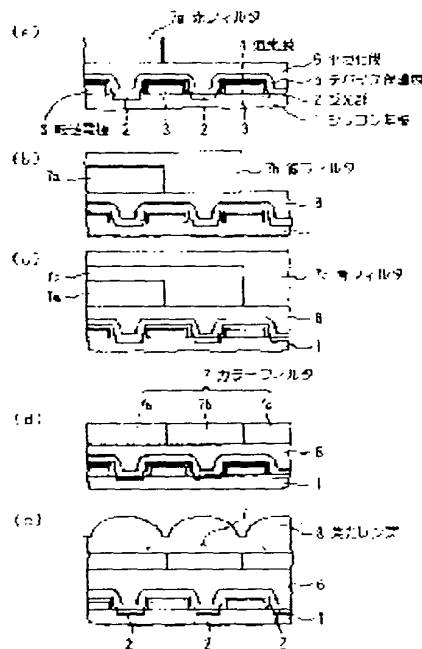
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(54) MANUFACTURE OF SOLID-STATE IMAGE PICK UP ELEMENT

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a method of manufacturing a solid-state image pick up device, which does not generate overlapping nor a gap the surface of the filter, which are formed adjacent to each other, of a color filter or between the adjacent filters and forms the device into a good form.

SOLUTION: A green filter 7b is formed on a flattened film 6 in such a way as to cover a red filter 7a and moreover, a blue filter 7c is formed in such a way as to cover the filter 7b. Then, each one part of the filters 7c, 7b and 7a is removed in order by an anisotropic etching, whereby a color filter 7 of a desired even thickness is formed. Thereby, an overlapping or a gap is never generated on the surfaces of the filters or between the adjacent filters and as the film thickness of the color filter can be formed thinner by a control of the anisotropic etching, variations of the characteristics, such as a sensitivity and a smear, of a solid-state image sensing element can be lessened.



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